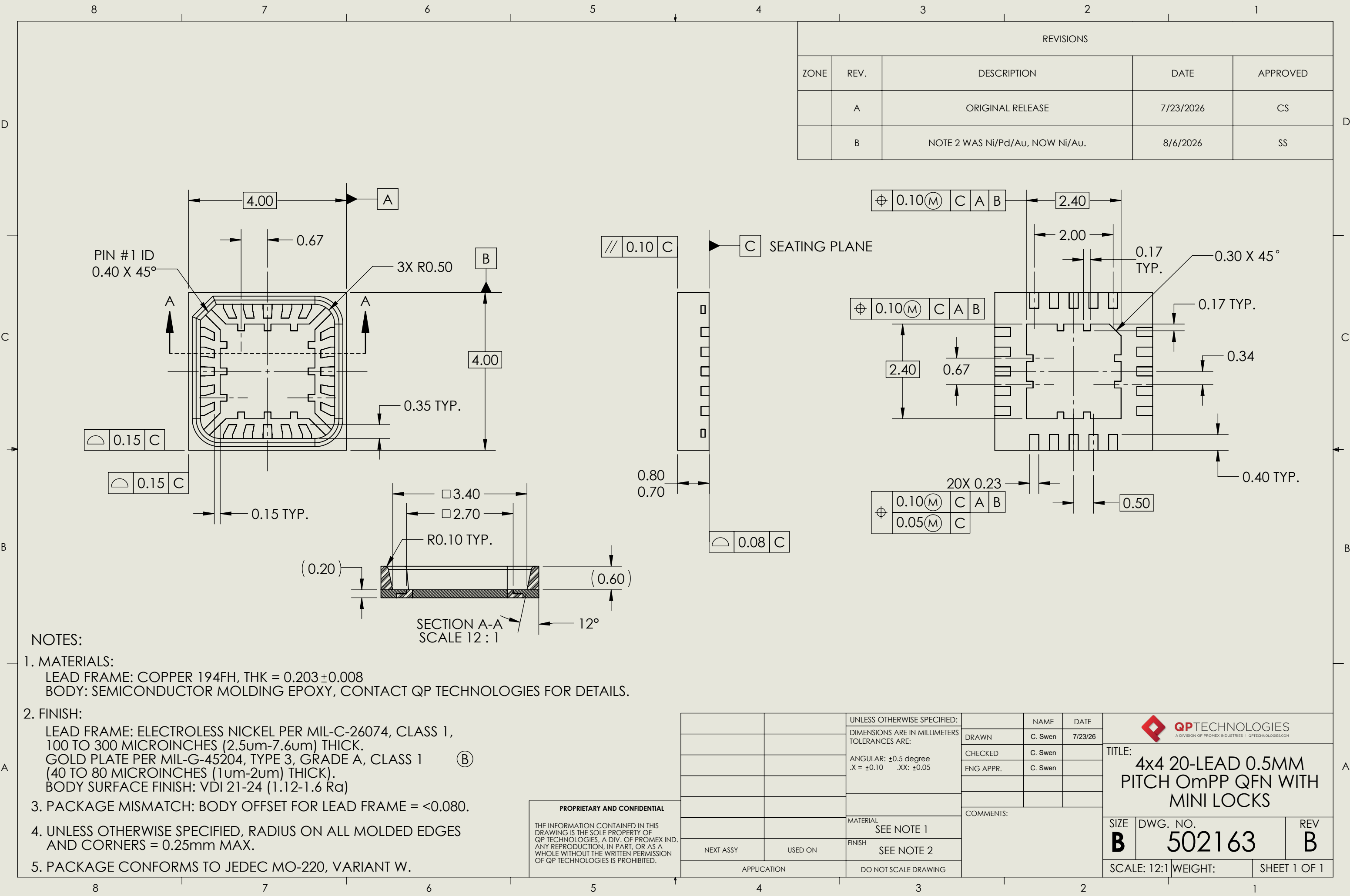




REVISIONS				
ZONE	REV.	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	7/23/2026	CS
	B	NOTE 2 WAS Ni/Pd/Au, NOW Ni/Au.	8/6/2026	SS

NOTES:

1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QP TECHNOLOGIES FOR DETAILS.
2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICROINCHES (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = <0.080.
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO-220, VARIANT W.

PROPRIETARY AND CONFIDENTIAL

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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.10 .XX: ±0.05		NAME	DATE	 QPTECHNOLOGIES A DIVISION OF PROMEX INDUSTRIES QPTECHNOLOGIES.COM			
			DRAWN	C. Swen	7/23/26				
			CHECKED	C. Swen		TITLE: 4x4 20-LEAD 0.5MM PITCH OmPP QFN WITH MINI LOCKS			
			ENG APPR.	C. Swen					
			COMMENTS:			SIZE B DWG. NO. 502163 REV B			
		MATERIAL SEE NOTE 1							
		FINISH SEE NOTE 2							
NEXT ASSY	USED ON					SCALE: 12:1		WEIGHT:	SHEET 1 OF 1
APPLICATION		DO NOT SCALE DRAWING							